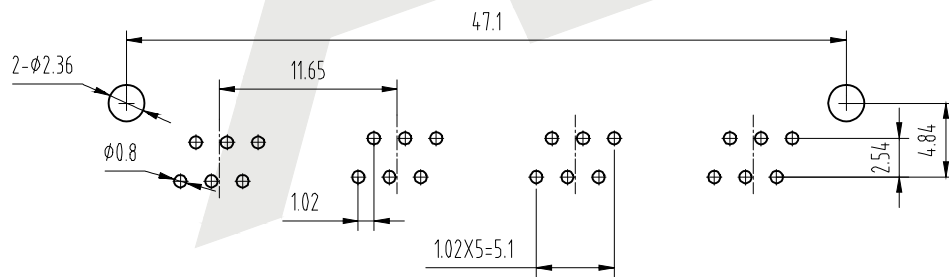
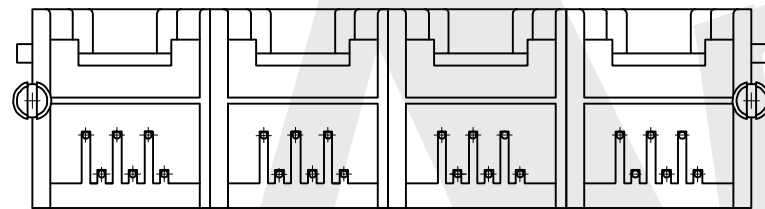
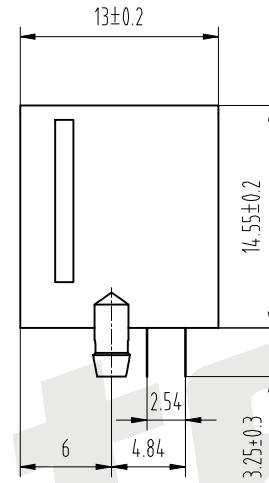
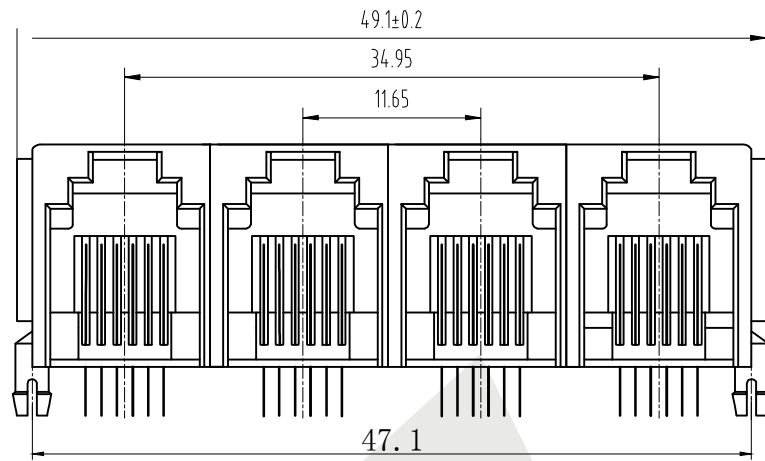


HSF



ROHS



PC Board Layout  
Component Side Shown

NOTES:  
MATERIAL:

1. HOUSING MATERIAL: GLASS FILLED POYESTER UL94V-0.
2. CONTACT MATERIAL: PHOSPHOR BRONZE  $t=0.3\text{mm}$
3. PLATING: SELECTING GOLD PLATING  $1\mu\sim 50\mu$  OVER NICKEL IN CONTACT AREA.  $150\mu$  TIN PLATIN. OVER NICKEL IN SOLDER AREA
4. SHIELD: 0.2mm THICKNESS COPPER WITH NICKEL PLATE

ELECTRICAL

1. VOLTAGE RATING: 125VAC RMS
2. CURRENT RATING: 1.5AMP
3. CONTACT RESISTANCE: 30MILLIOHMS MAX
4. INSULATION RESISTANCE 500MEGOHMS MIN @500V DC
5. DIELECTRIC WITHSTANDING RESISTANCE : 1000V AC RMS 50Hz. 1MIN

MECHANICAL

1. DURRABILITY: 750 CYCLES MIN
2. PCB RETENTON PRB-SOLDER: 1 LB MIN

REIVIRONMENTAL

1. STORAGE:  $-40^{\circ}\text{C}$  TO  $85^{\circ}\text{C}$
2. OPERATION:  $0^{\circ}\text{C}$  TO  $70^{\circ}\text{C}$

Order code:

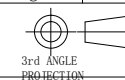
ATRJ5522 - 6P - 6C - X - A - C - A

① ② ③ ④ ⑤ ⑥ ⑦

- ① SERIES NO:
- ② NUMBER OF POSITIONS (8P, 6P, 4P)
- ③ NUMBER OF CONTACTS (8C, 6C, 4C)
- ④ Contact Plating  
G0: Gold flash  
G1: 3U" Gold  
G2: 5U" Gold  
G3: 10U" Gold  
G4: 15U" Gold  
G5: 30U" Gold  
SN: Tin
- ⑤ Shield  
A: W/O Shield  
B: Half Shield  
C: Shield W/Eml  
D: Shield W/O Eml
- ⑥ Ports  
A: 1X1P  
B: 1X2P  
C: 1X4P  
D: 1X5P  
E: 1X6P  
F: 1X8P
- ⑦ With Panel or not  
A: With panel  
B: Without panel

Unless Otherwise specified tolerance  
X.  $\pm 0.35$  X.XX:  $\pm 0.20$   
X.X:  $\pm 0.25$  X.XXX:  $\pm 0.15$

SCALE: As Shown UNIT: mm  
DRAW Wu Feng Rong DATE 07/09/2019  
CHECK BobYang DATE 07/09/2019



**Antenk**® ANTENK ELECTRONICS CO.,LTD  
Http://www.antenk.com  
E-mail:sales@antenk.com

TITLE: RJ11 Jack side entry,  
Full Plastic 1X4P with panel

DRAWING NO: ATRJ5522-6P6C-X-A-C-A

PRODUCT NO: ATRJ5522-6P6C-X-A-C-A

REV	DESCRIPTION	DATE
1		
2		
3		
4		
5		